

Amendments of the Specification

Please replace the paragraph at page 2, lines 10-31 with the following new paragraph:

Therefore, it is highly desirable to develop a new method for electrolytic tin plating. Tin-lead alloy has a melting point lower than that of tin and the lead present in the alloy also functions as a brightening agent. As a result, electrolytic plating of the tin-lead alloy is able to generate a fine and tightly deposited film with very stable properties. In addition, the deposited film has excellent solder wettability. On the other hand, electrolytic tin plating usually generates a rough plating film with poor solder wettability. By using a brightening agent, including organic brightening agents, such as aldehyde analogs, etc., or amine-based brightening agent, such as ammonium salt, etc., it is possible to form a fine and tightly deposited film with improved solder wettability immediately after plating. However, the content of organic substances in the plating film will increase and solder wettability may deteriorate as a function of time. For the tin or solder plating film on the electrodes and wires on the electronic parts made of ceramic, glass, plastic, etc., sufficient solder wettability can be achieved for the parts with a size of 1005 type or higher. However, when the parts has a size of 1005 type or lower, the tin-plating film may not have sufficient solder wettability, resulting in poor connection. For the electronic parts made of ceramic, glass, etc., in order to avoid erosion of the base material or metal deposition on the base material, it is necessary to use a weak acidic or neutral plating solution. Particularly, ammonium salts are very corrosive to the base material and should not be used for this purpose. Therefore, it is ~~high~~ highly desirable to develop an electrolytic tin-plating solution and a method for electrolytic tin plating using the solution, which has minimum erosion to the base material and is capable of generating a plating film with the same level of solder wettability as that of a tin-lead alloy plating film.